Dual Buffer with 3-State Outputs

The NL27WZ126 is a high performance dual noninverting buffer operating from a 1.65 V to 5.5 V supply.

Features

- Extremely High Speed: t_{PD} 2.6 ns (typical) at $V_{CC} = 5.0 \text{ V}$
- Designed for 1.65 V to 5.5 V V_{CC} Operation
- Over Voltage Tolerant Inputs and Outputs
- LVCMOS Compatible
- 24 mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current Substantially Reduces System Power Requirements
- 3-State OE Input is Active-High
- Replacement for NC7WZ126
- Chip Complexity = 72 FETs
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

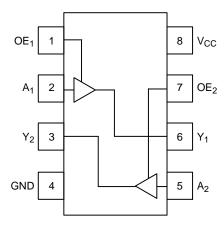


Figure 1. Pinout (Top View)

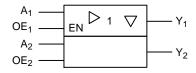


Figure 2. Logic Symbol



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MARKING DIAGRAM



US8 US SUFFIX CASE 493



M2 = Device Code
M = Date Code*

Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation may vary depending upon manufacturing location.

PIN ASSIGNMENT

Pin	Function
1	OE
2	A ₁
3	Y ₂
4	GND
5	A ₂
6	Y ₁
7	OE ₂
8	V _{CC}

FUNCTION TABLE

In	Output	
OE _n	An	Yn
Н	Н	Н
Н	L	L
L	Х	Z

X = Don't Caren = 1, 2

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

MAXIMUM RATINGS

Symbol	Parameter	Value	Units
V _{CC}	DC Supply Voltage	-0.5 to +7.0	V
VI	DC Input Voltage	-0.5 to +7.0	V
Vo	DC Output Voltage	-0.5 to +7.0	V
I _{IK}	DC Input Diode Current VI < GND	-50	mA
lok	DC Output Diode Current V _O < GND	-50	mA
Io	DC Output Sink Current	±50	mA
I _{CC}	DC Supply Current per Supply Pin	±100	mA
I _{GND}	DC Ground Current per Ground Pin	±100	mA
T _{STG}	Storage Temperature Range	-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
TJ	Junction Temperature under Bias	+150	°C
θ_{JA}	Thermal Resistance (Note 1)	250	°C/W
P _D	Power Dissipation in Still Air at 85°C	250	mW
MSL	Moisture Sensitivity	Level 1	
F _R	Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
V _{ESD}	ESD Withstand Voltage Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	> 2000 > 200 N/A	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.
- Tested to EIA/JESD22-A114-A.
 Tested to EIA/JESD22-A115-A.
- 4. Tested to JESD22-C101-A.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Units
V _{CC}	Supply Voltage Operating Data Retention Only	1.65 1.5	5.5 5.5	V
VI	Input Voltage (Note 5)	0	5.5	V
Vo	Output Voltage (HIGH or LOW State)	0	5.5	V
T _A	Operating Free–Air Temperature	-40	+85	°C
Δt/ΔV	Input Transition Rise or Fall Rate $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$ $V_{CC} = 3.0 \text{ V} \pm 0.3 \text{ V}$ $V_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V}$	0 0 0	20 10 5	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

5. Unused inputs may not be left open. All inputs must be tied to a high- or low-logic input voltage level.

DC ELECTRICAL CHARACTERISTICS

			V _{CC}	T _A = 25°C		-40°C ≤ T _A ≤ 85°C			
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Units
V _{IH}	High-Level Input Voltage		1.65 2.3 to 5.5	0.75 V _{CC} 0.7 V _{CC}			0.75 V _{CC} 0.7 V _{CC}		V
V _{IL}	Low-Level Input Voltage		1.65 2.3 to 5.5			0.25 V _{CC} 0.3 V _{CC}		0.25 V _{CC} 0.3 V _{CC}	V
V _{OH}	High-Level Output Voltage V _{IN} = V _{IH}	$I_{OH} = 100 \mu A$ $I_{OH} = -8 \text{ mA}$ $I_{OH} = -12 \text{ mA}$ $I_{OH} = -16 \text{ mA}$ $I_{OH} = -24 \text{ mA}$ $I_{OH} = -32 \text{ mA}$	1.65 to 5.5 1.65 2.7 3.0 3.0 4.5	V _{CC} - 0.1 1.9 2.2 2.4 2.3 3.8	V _{CC} 2.1 2.4 2.7 2.5 4.0		V _{CC} - 0.1 1.9 2.2 2.4 2.3 3.8		V
V _{OL}	Low-Level Output Voltage V _{IN} = V _{IH} or V _{IL}	$\begin{split} I_{OL} &= 100 \ \mu\text{A} \\ I_{OL} &= 8 \ \text{mA} \\ I_{OL} &= 12 \ \text{mA} \\ I_{OL} &= 16 \ \text{mA} \\ I_{OL} &= 24 \ \text{mA} \\ I_{OL} &= 32 \ \text{mA} \end{split}$	1.65 to 5.5 1.65 2.7 3.0 3.0 4.5		0.20 0.22 0.28 0.38 0.42	0.1 0.3 0.4 0.4 0.55 0.55		0.1 0.3 0.4 0.4 0.55 0.55	V
I _{IN}	Input Leakage Current	V _{IN} = 5.5V or GND	0 to 5.5			±0.1		±1.0	μΑ
I _{OFF}	Power Off Leakage Current	V _{IN} = 5.5V or V _{OUT} = 5.5 V	0			1		10	μΑ
I _{CC}	Quiescent Supply Current	V _{IN} = 5.5V or GND	5.5			1		10	μΑ
I _{OZ}	3-State Output Leakage	$V_{IN} = V_{IL} \text{ or } V_{IH}$ $0 \text{ V} \le V_{OUT} \le 5.5 \text{ V}$	1.65 to 5.5			±0.5		±5	μА

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

AC ELECTRICAL CHARACTERISTICS ($t_R = t_F = 3.0 \text{ ns}$)

			V _{CC}	T _A = 25°C -40°C ≤		-40°C ≤ T	A ≤ 85°C		
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Units
t _{PLH} t _{PHL}	Propagation Delay AN to YN (Figures 3 and 4, Ta-	$R_L = 1 \text{ M}\Omega, C_L = 15 \text{ pF}$	1.8 ± 0.15 2.5 ± 0.2	2.0 1.0		12 7.5	2.0 1.0	13 8	ns
	ble 1)	$\begin{aligned} R_L &= 1 \text{ M}\Omega, \ C_L = 15 \text{ pF} \\ R_L &= 500 \ \Omega, \ C_L = 50 \text{ pF} \end{aligned}$	3.3 ± 0.3	0.8 1.2		5.2 5.7	0.8 1.2	5.5 6.0	
		$\begin{aligned} R_L &= 1 \text{ M}\Omega, \ C_L = 15 \text{ pF} \\ R_L &= 500 \ \Omega, \ C_L = 50 \text{ pF} \end{aligned}$	5.0 ± 0.5	0.5 0.8		4.5 5.0	0.5 0.8	4.8 5.3	
toslh	Output to Output Skew	$R_L = 500 \Omega, C_L = 50 pF$	3.3 ± 0.3			1.0		1.0	ns
toshl	(Note 6)	$R_L = 500 \Omega, C_L = 50 pF$	5.0 ± 0.5			0.8		0.8	
t _{PZH}	Output Enable Time (Figures 5, 6 and 7, Ta- ble 1)	$R_L = 250 \ \Omega, \ C_L = 50 \ pF$	1.8 ± 0.15 2.5 ± 0.2	3.0 1.8		14 8.5	3.0 1.8	15 9.0	ns
	ble i)		3.3 ± 0.3	1.2		6.2	1.2	6.5	
			5.0 ± 0.5	0.8		5.5	0.8	5.8	
t _{PHZ}	Output Enable Time (Figures 5, 6 and 7, Ta-	R_L & R1 = 500 Ω, C_L = 50 pF	1.8 ± 0.15 2.5 ± 0.2	2.5 1.5		12 8.0	2.5 1.5	13 8.5	ns
	ble 1)		3.3 ± 0.3	0.8		5.7	0.8	6.0	
			5.0 ± 0.5	0.3		4.7	0.3	5.0	

Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device.
 This specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}); parameter guaranteed by design.

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Units
C _{IN}	Input Capacitance	$V_{CC} = 5.5 \text{ V}, V_I = 0 \text{ V or } V_{CC}$	2.5	pF
C _{OUT}	Output Capacitance	$V_{CC} = 5.5 \text{ V}, V_I = 0 \text{ V or } V_{CC}$	2.5	pF
C _{PD}	Power Dissipation Capacitance (Note 7)	10 MHz, V _{CC} = 3.3 V, V _I = 0 V or V _{CC} 10 MHz, V _{CC} = 5.5 V, V _I = 0 V or V _{CC}	9 11	pF

^{7.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$. C_{PD} is used to determine the no–load dynamic power consumption; $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.

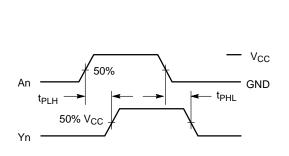
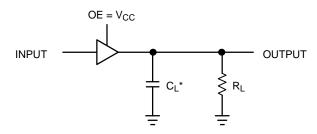


Figure 3. Switching Waveform



*Includes all probe and jig capacitance.

A 1 MHz square input wave is recommended for propagation delay tests.

Figure 4. t_{PLH} or t_{PHL}

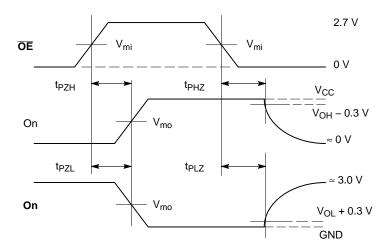
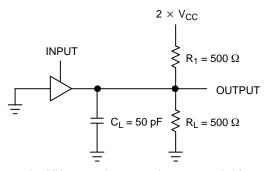


Figure 5. AC Output Enable and Disable Waveform

Table 1. Output Enable and Disable Times

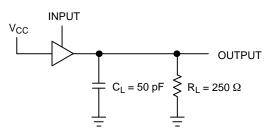
 t_R = t_F = 2.5 ns, 10% to 90%; f = 1 MHz; t_W = 500 nsv

	V _{CC}				
Symbol	3.3 V ± 0.3 V	2.7 V	2.5 V ± 0.2 V		
V _{mi}	1.5 V	1.5 V	V _{CC/} 2		
V _{mo}	1.5 V	1.5 V	V _{CC/} 2		



A 1 MHz square input wave is recommended for propagation delay tests.

Figure 6. t_{PZL} or t_{PLZ}



A 1 MHz square input wave is recommended for propagation delay tests.

Figure 7. t_{PZH} or t_{PHZ}

DEVICE ORDERING INFORMATION

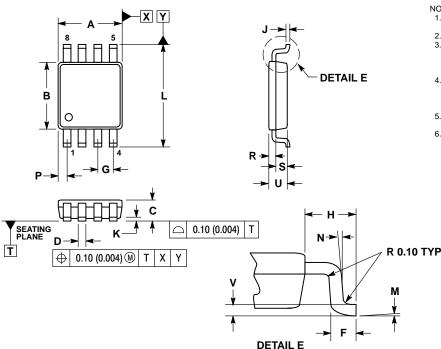
Device Order Number	Package Type	Shipping [†]
NL27WZ126USG	US8 (Pb-Free)	3000 / Tape & Reel
NLV27WZ126USG*	(1 b-11ee)	

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

PACKAGE DIMENSIONS

US8 CASE 493-02 ISSUE D



NOTES

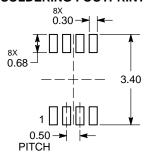
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETERS.
- CONTROLLING DIMENSION: MILLIMETERS.
 DIMENSION A DOES NOT INCLUDE MOLD
 FLASH, PROTRUSION OR GATE BURR. MOLD
 FLASH, PROTRUSION AND GATE BURR SHALL
 NOT EXCEED 0.14MM (0.0055") PER SIDE.
 DIMENSION B DOES NOT INCLUDE INTERLEAD
 FLASH OR PROTRUSION. INTERLEAD FLASH
 AND PROTRUSION SHALL NOT EXCEED 0.14MM
 (0.0056") BDED SIDE.
- (0.0055") PER SIDE. LEAD FINISH IS SOLDER PLATING WITH
- THICKNESS OF 0.0076-0.0203MM (0.003-0.008"). ALL TOLERANCE UNLESS OTHERWISE SPECIFIED ±0.0508MM (0.0002")

MILLIN	IETERS	INC	HES
MIN	MAX	MIN	MAX
1.90	2.10	0.075	0.083
2.20	2.40	0.087	0.094
0.60	0.90	0.024	0.035
0.17	0.25	0.007	0.010
0.20	0.35	0.008	0.014
0.50	BSC	0.020	BSC
0.40	REF	0.016	REF
0.10	0.18	0.004	0.007
0.00	0.10	0.000	0.004
3.00	3.20	0.118	0.128
0 °	6 °	0 °	6°
0 °	10 °	0 °	10 °
0.23	0.34	0.010	0.013
0.23	0.33	0.009	0.013
0.37	0.47	0.015	0.019
0.60	0.80	0.024	0.031
	MIN 1.90 2.20 0.60 0.17 0.20 0.50 0.40 0.10 0.00 3.00 0° 0.23 0.23 0.37	1.90 2.10 2.20 2.40 0.60 0.90 0.17 0.25 0.20 0.35 0.50 BSC 0.40 REF 0.10 0.18 0.00 0.10 3.00 3.20 0° 6° 0° 10° 0.23 0.34 0.23 0.33 0.37 0.47	MIN MAX MIN 1.90 2.10 0.075 2.20 2.40 0.087 0.60 0.90 0.024 0.17 0.25 0.007 0.20 0.35 0.088 0.50 BSC 0.026 0.40 REF 0.016 0.10 0.18 0.004 0.00 0.10 0.000 3.00 3.20 0.118 0° 6° 0° 0° 10° 0° 0.23 0.34 0.010 0.23 0.33 0.009 0.37 0.47 0.015

0.005 BSC

0.12 BSC

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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